

ABSTRACT

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The semiconductor device (A) comprises a semiconductor chip (3), a protective package (4) covering the semiconductor chip (3), a first lead (1), and a second lead (2). The semiconductor chip (3) is placed at an inner end (10a) of the first lead (3) (1). Further, the semiconductor chip (3) is connected to an inner end (20a) of the second lead (2) via a wire (W). The first lead (1) includes an outer portion (11) extending out of the protective package (4) whereas the second lead (2) includes an outer portion (21) extending out of the protective package (4). These two outer portions (11, 21) are flat.